

ABSTRACT OF THE DISCLOSURE

A semiconductor package and a fabrication method thereof can enhance adhesion between a solder and a package body by employing an irregular metal pattern, and improve stability. The semiconductor package includes a semiconductor substrate; a plurality of chip pads separately formed on an upper surface of the semiconductor substrate; an irregular metal pattern electrically connected to the plurality of chip pads; and an external terminal electrically connected to the metal pattern. In addition, a method of fabricating the semiconductor package includes the steps of separately forming a plurality of chip pads on an upper surface of a semiconductor substrate; forming an irregular metal pattern electrically connected to the plurality of chip pads; and forming an external terminal electrically connected to the metal pattern.